



## Standard Assembly Build Sheet (Air Cavity - OmPP, OcPP, Ceramic, etc.)

Original request

Changed request

Rev # \_\_\_\_\_

QP Internal S.O. #: \_\_\_\_\_

QP Quote #: \_\_\_\_\_

QP Sales Contact: \_\_\_\_\_

### CUSTOMER CONTACT INFORMATION

Company: \_\_\_\_\_

Contact Name: \_\_\_\_\_ Date: \_\_\_\_\_

Phone: \_\_\_\_\_

Email: \_\_\_\_\_

P.O. #: \_\_\_\_\_

Is this item under the jurisdiction of the International Traffic in Arms Regulations (ITAR)? Yes No

### DELIVERY REQUEST

LEAD TIMES WILL VARY BASED ON SCOPE OF WORK AND QUANTITY. STANDARD LEAD TIME FOR BENCHMARK ORDER (PKG: OmPP, PKG QTY: &lt;100, WIRE COUNT: &lt;50, SINGLE DIE ATTACH) IS 3 DAYS. EXPEDITE (1-2 DAYS). PREMIUM (8 HRS).

Standard

Expedite

Premium

### DIE INFORMATION:

ALL WAFER PROCESSING REQUIRES A BACKGRIND/DICING BUILD SHEET TO BE COMPLETED AND ATTACHED SEPARATELY.

Die Format: Waffle Pack Gel-Pak Diced Wafer on Tape Wafer (requires processing) Other: \_\_\_\_\_

Die Size: \_\_\_\_\_ X \_\_\_\_\_  $\mu$ m or mils

(a) Wafer ID/Die ID:

(b) Lot #

(c) Qty of Devices to be Assembled from ID

Pad Pitch: \_\_\_\_\_ X \_\_\_\_\_  $\mu$ m or mils Bond

1a. \_\_\_\_\_

1b. \_\_\_\_\_

1c. \_\_\_\_\_

Pad Dims: \_\_\_\_\_ X \_\_\_\_\_  $\mu$ m or mils Bond

2a. \_\_\_\_\_

2b. \_\_\_\_\_

2c. \_\_\_\_\_

Pad Opening: \_\_\_\_\_ X \_\_\_\_\_  $\mu$ m or mils

3a. \_\_\_\_\_

3b. \_\_\_\_\_

3c. \_\_\_\_\_

Thickness: \_\_\_\_\_  $\mu$ m or mils

4a. \_\_\_\_\_

4b. \_\_\_\_\_

4c. \_\_\_\_\_

Metalization: Aluminum Gold Other (Specify): \_\_\_\_\_

Probed?

Passivated?

### DEVICE INFORMATION

Device Name: \_\_\_\_\_ Pin Count: \_\_\_\_\_ Lead Pitch: \_\_\_\_\_ Die Per Package: \_\_\_\_\_ Wire Count Per Package: \_\_\_\_\_

Qty of Devices to be Assembled: \_\_\_\_\_ Body Size (mm): \_\_\_\_\_ X \_\_\_\_\_

Packages provided by: Customer Quik-Pak Packages Require Opening (OcPP)

Package Type: OmPP (QFN/SOIC) Ceramic Other: \_\_\_\_\_

Package Description: \_\_\_\_\_

### SPECIAL INSTRUCTIONS (ATTACH ADDITIONAL DOCUMENTS IF NEEDED)

### CUSTOMER FURNISHED MATERIALS:

PLEASE LIST ANY ADDITIONAL CFMs THAT WILL BE SHIPPED TO QUIK-PAK. IF MORE SPACE IS NEEDED, ATTACH ADDITIONAL DOCUMENTS.

1. \_\_\_\_\_ 2. \_\_\_\_\_ 3. \_\_\_\_\_

4. \_\_\_\_\_ 5. \_\_\_\_\_ 6. \_\_\_\_\_

7. \_\_\_\_\_ 8. \_\_\_\_\_ 9. \_\_\_\_\_

## ASSEMBLY FLOW

ALL WIRE BONDING REQUIRES A BONDING DIAGRAM BE ATTACHED WITH CLEARLY LABELED PIN 1, DIE ORIENTATION, AND WIRES BONDS.

Please Indicate The File Format: CAD Drawing Other (JPEG, PowerPoint, PDF, etc.)

Select Die From: Center of Wafer(s) Wafer Map(s) Reticle Map-include with Build Sheet

Die Attach Material (ENTER QTY IF SEPARATE LOTS REQUIRE DIFFERENT MATERIALS):

\_\_\_\_ Conductive Epoxy      \_\_\_\_ High Thermally Conductive/Electrically Non-Conductive  
\_\_\_\_ Non-Conductive Epoxy      \_\_\_\_ High Thermally Conductive/Electrically Conductive Material

Gold Wire Diameter (ENTER QTY IF SEPARATE LOTS REQUIRE DIFFERENT WIRE DIAMETER):

\*STANDARD MATERIAL. OTHER OPTIONS MAY INCREASE COST/LEADTIME.

\_\_\_\_ 0.7 mil      \_\_\_\_ 0.8 mil      \_\_\_\_ 1.0 mil\*      \_\_\_\_ 1.2 mil  
\_\_\_\_ 1.3 mil      \_\_\_\_ 1.5 mil      \_\_\_\_ 2.0 mil      \_\_\_\_ Other (AI available - call for wire size)

Die to Die Bond      Lead to Down Bond (or jumper wire)      Lead to Lead Bond

Gold Ribbon: \_\_\_\_ 1 X 2 mil      \_\_\_\_ 1 X 3 mil      \_\_\_\_ 1 X 4 mil

Lead Trim? Yes No Requested Lead Length: \_\_\_\_\_ mil

Seal (ENTER QTY IF SEPARATE LOTS REQUIRE DIFFERENT SEALING METHODS):

\_\_\_\_ None      \_\_\_\_ Encapsulation Around Leads Only      Removable Lid (For Walled Packages):  
\_\_\_\_ Standard Full Encapsulation (Glop Top)      \_\_\_\_ Frame & Lid (For Non-Solder Applications)      \_\_\_\_ Epoxy on 4 Corners  
\_\_\_\_ Remolded / Flattened (Jedec std.)      \_\_\_\_ Solder Sealed Lids      \_\_\_\_ Epoxy on 2 Corners  
\_\_\_\_ Clear encapsulant (UV Cure)      \_\_\_\_ Epoxy Seal Lid      \_\_\_\_ Taped on Lids  
\_\_\_\_ Other (Specify) \_\_\_\_\_

Marking (MAX CHARACTER LENGTH AND NUMBER OF ROWS WILL VARY BASED ON PACKAGE SIZE. CONTACT QP FOR DESIGN APPROVAL AND COSTS.):

Hand Mark pin 1 on device?

Custom Design

No Custom Marking

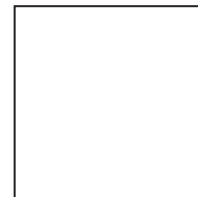
Hand Mark (Max. 1-3 characters): \_\_\_\_\_

Pad Print (White on Black) - E-mail artwork in native .EPS or .AI file format

Laser Mark (Black on Black) - E-mail artwork in native .EPS or .AI file format

Serialization (MAY INCREASE MARKING COSTS/LEADTIME). Please describe:

\_\_\_\_\_  
\_\_\_\_\_



Please mark pin 1 corner and indicate how marking should appear on package relative to pin 1.

## SHIPPING (Contact QP with any special requests)

Reject Parts Disposition: Return to Customer Bag and Tag Destroy

\*Unless otherwise noted all extra materials will be returned.

Shipping Method (Please Select)

Account #: \_\_\_\_\_

Pickup

FedEx

DHL

UPS

Courier

Special Instructions

Ship To Address (Finished Product):

Attn: \_\_\_\_\_

Address: \_\_\_\_\_

\_\_\_\_\_

Ship To Address (Excess Die and Materials):

Attn: \_\_\_\_\_

Address: \_\_\_\_\_

\_\_\_\_\_

Include Certificate of Conformance

Ship Materials In

Trays

Tubes

Other: \_\_\_\_\_

Containers Provided

Quik-Pak

Customer

***For Quik-Pak Internal Use Only:***

Orders meeting one of the following requirements require signatures by representatives in the following departments:

☐ Over \$20k      ☐ ISO-13485 Processing      ☐ Change in instructions after order has been released to production

Sales: \_\_\_\_\_ Date: \_\_\_\_\_

Engineering: \_\_\_\_\_ Date: \_\_\_\_\_

Manufacturing: \_\_\_\_\_ Date: \_\_\_\_\_

QA: \_\_\_\_\_ Date: \_\_\_\_\_

Per Quik-Pak quality program, risk assessment is required on orders over \$100k and/or Medical orders built under ISO-13485 std.